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DELPHI TECHNOLOGIES, INC.  
Legal Staff Mail Code CT10C  
P.O. Box 9005  
Kokomo, Indiana 46904-9005

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Box Patent Applications  
Assistant Commissioner for Patents  
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No. : DP-305031

Inventor(s) : Shing Yeh  
Bradley H. Carter  
Curtis W. Melcher

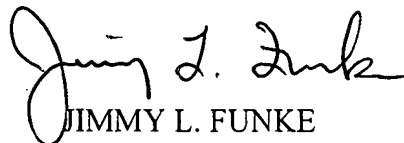
Title : LEAD-FREE SOLDER ALLOY AND SOLDER REFLOW PROCESS

Address all correspondence to:

JIMMY L. FUNKE  
DELPHI TECHNOLOGIES, INC.  
Legal Staff Mail Code CT10C  
P.O. Box 9005  
Kokomo, Indiana 46904-9005


Telephone : (248) 267-5554

Very Truly Yours,

  
JIMMY L. FUNKE  
Reg. No. 34166

Enclosures

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